



Nested Processors, Virtual Memory, Hardware Platforms

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Approach

Hardware platform and virtual hardware platform

Processor, memory, bus without subcomponents



Processor and Virtual Processor

Separate Hardware and Software concerns

Processor: specification of hardware aspects (chip, core, multi-threads)

Virtual Processor: (OS, partitions, schedulers)

Processor binding points: for cycles and storage

V3 proposal: Virtual Processor no longer contained in a processor

Virtual Processor

Logical resource with capacity/budget

Containment region

“Nested” Processor and hardware platform

processor as system (platform) subcomponent

Properties to describe hardware constraints (endianness)



Bus & Virtual Bus

- Separation of physical and logical concerns
 - Binding of logical to physical
- Bus
 - Physical entity for transferring data
 - Use for physical resource transfer? Fluids, electricity
 - Similar to question of ports with data/event communication
- Virtual bus
 - Logical channel resource with resource capacity/budget
 - Containment region for security/safety
 - Protocol with wrapper overhead
- Bus as system (platform) subcomponents
 - Subcomponents as binding points
 - Network architecture with AADL bus to bus connectivity



Memory & Virtual Memory

- Separation of physical and logical concerns
 - Binding of logical to physical
- Memory
 - Storage with binding points
 - Need for representing different section of memory addresses: binding points have properties to indicate base address and range (size)
 - Memory binding point on devices can model device registers without requiring memory subcomponents.
- Virtual memory roles
 - Represent logical addresses that are mapped to addresses in different components in the platform
 - Logical resource with capacity/budget
 - Logical containment regions
 - Represent segments of address space
- Memory as system (platform) subcomponents
 - Subcomponents as binding points
 - Memory system architecture with connectivity via bus
 - Platform with memory and processor



Platform & Virtual platform

- System implementation
 - Physical system model
 - Memory, bus, processor as leaves
 - Visibility for configuration
 - Visibility of binding points
- Virtual platform
 - Connectivity between virtual buses, virtual processors, virtual memory
- Processor, memory, bus, device implementations
 - Implementation of configured component with explicit choice points
 - Visibility boundary for choice points and binding points
 - Implementation of protocols, etc.



Platforms and Physical Systems

- Hardware platforms & physical systems
 - Restrictions on subcomponents
 - Properties for physical characteristics
- Physical features
 - Separate from generic (abstract) features
- Separate category vs. property/model constraint
 - Platform, virtual platform, physical



Summary/Actions

- No nested processors, memory, buses: composition via system
 - No virtual x as subcomponent of x: handled by bindings
 - Virtual platform with connectivity between virtual bus, virtual processor, virtual memory
 - Composition through system component: no new platform category
 - Virtual memory and binding points: work examples to validate need for both
 - Features: non-directional, directional, bi-directional
 - Observable feature: for reasoning and for actual observation
 - Physical features: draft proposal of description and properties. Don't reinvent but align with SysML and Modelica
 - Need for physical component? Nested physical component?
 - Binding -> allocation
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- Alignment of spec sheet for variants with component type?

